

## **AMENDMENTS TO THE SPECIFICATION**

On page 12, please replace the paragraph beginning at line 1 with the following:

The exposure station 20 shown in Figure 1 has a UV-lamp 21 and a reflector 22 which focuses the UV-radiation emitted by the UV-lamp 21 on to the film 53. The power of the UV-lamp 21 is so selected in that situation that, as it passes through the exposure station 22, the adhesive layer 57 is irradiated with a sufficient amount of energy which ensures reliable hardening of the adhesive layer 57. As shown in Figure 1 the film 53 is irradiated in that case from the side of the carrier film 45. That is possible if a transparent or semi-transparent layer is used as the electrical functional layer 47 [57], for example a thin metal layer of a nature as set forth in hereinbefore. In addition it is necessary for that purpose for the carrier film 45 and the release layer 46 to comprise a UV-transparent material. If, by virtue of the specific composition of the electrical functional layer 47, it should not be possible to make that layer UV-transparent or semi-transparent, it is possible for the film 53 to be irradiated with UV-light from the side of the base film 51 [53]. In that case the base film 51 [53] would then have to be UV-transparent in nature.

On page 17, please replace the paragraph beginning at line 11 with the following:

The film body shown in Figure 5c now forms a base film to which an electrical functional layer 94 [97] is applied by means of one of the processes shown in Figure 1, Figure 2 or Figure 3. Figure 5c shows the resulting film body comprising the carrier film 91, the lacquer layer 92, the adhesive layer 93, the electrical functional layer 94, the semiconducting layer 95, the adhesive layer 96 and the electrical functional layer 97.